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| Application Number     | 10/816,179     |
| Filing Date            | March 31, 2004 |
| First Named Inventor   | Chung J. Lee   |
| Art Unit               | 1763           |
| Examiner Name          | Rudy Zervigon  |
| Attorney Docket Number | DSI302         |

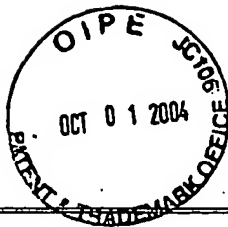
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Date  
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SHEET 1 OF 1

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|--|---|-----------------------------------|---------------|----------------------------------|--------------|-------------------------|
| FORM PTO-1449  |   | DOCKET NUMBER<br>DSI 302          |               | APPLICATION NUMBER<br>10/816,179 |              |                         |
| INFORMATION DISCLOSURE<br>CITATION IN AN APPLICATION |   | APPLICANTS<br>Chung J. Lee et al. |               |                                  |              |                         |
|  |   | FILING DATE<br>March 31, 2004     |               | GROUP ART UNIT<br>1763           |              |                         |
| U.S. PATENT DOCUMENTS                                |   |                                   |               |                                  |              |                         |
| EXAMINER<br>INITIAL                                  | DOCUMENT<br>NUMBER  | DATE                              | NAME          | CLASS                            | SUB<br>CLASS | FIL. DATE<br>IF APPROP. |
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|  |   |                                   |               |                                  |              |                         |
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| OTHER DOCUMENTS                                      |   |                                   |               |                                  |              |                         |
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| EXAMINER   |   | DATE CONSIDERED                   |               |                                  |              |                         |